



RMA258-15R Sn10/Pb88/Ag2



RMA Solder Paste

Features:

- Long Pause-to-Print Capabilities
- Enhances Fine Print Definitions
- No Head-in-Pillow
- Excellent Wetting, Even Leadless Devices
- Exceptional Reflow During Long, Hot Profiles
- Reduced Voiding

Description:

RMA258-15R is a rosin based solder paste that has been developed to offer long pause-to-print capabilities while enhancing fine print definitions. RMA258-15R reduces such defects as voiding and eliminates head-in-pillow. The superior wetting ability of RMA258-15R results in bright, smooth and shiny solder joints. RMA258-15R is capable of exceptional reflow during long, hot profiles. RMA258-15R leaves medium, amber-colored post process residues.

Printing:

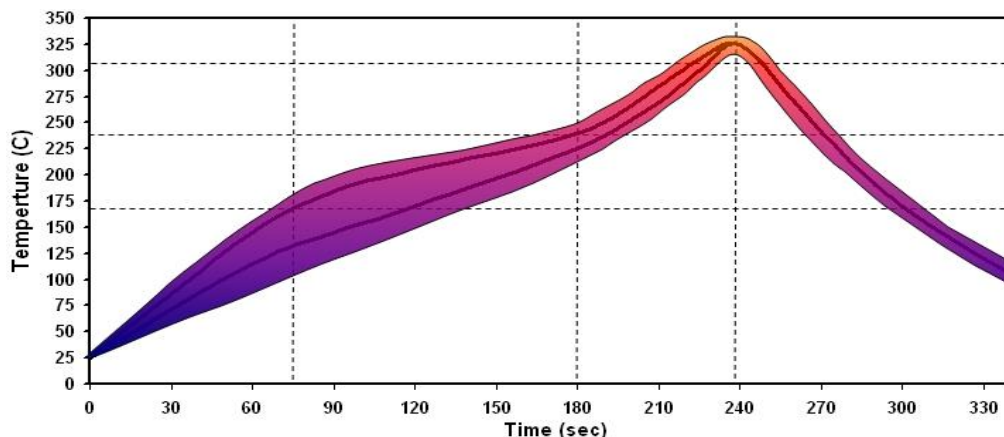
- Apply sufficient paste to the stencil to allow a smooth, even roll during the print cycle (a bead diameter of 12 to 16 mm (1/2 to 5/8 inch) is normally sufficient to begin).
- Apply small amounts of fresh solder paste to the stencil at controlled intervals to maintain paste chemistry and workable properties.
- RMA258-15R provides the necessary tack time and force for today's high speed placement equipment, which will enhance product performance and reliability.
- Cleaning of your stencil will vary by application; however, it can be accomplished using AIM DJAW-10 stencil cleaner.

RECOMMENDED INITIAL PRINTER SETTINGS BELOW ARE DEPENDENT ON PCB AND PAD DESIGN

PARAMETER	RECOMMENDED INITIAL SETTINGS	PARAMETER	RECOMMENDED INITIAL SETTINGS
Squeegee Pressure	0.9 - 1.5 lbs/inch of blade	PCB Separation Distance	0.75-2.0 mm (.030-.080")
Squeegee Speed	0.5 - 6 inches/second	PCB Separation Speed	3.0 – 20.0 mm/second
Snap-off Distance	On Contact 0.00 mm (0.00")		

Reflow Profile:

For circuit board assembly applications either a straight ramp-spike or ramp-soak-spike profile can be used as shown below. Both profiles would have a similar peak temperature and time above liquidus (TAL). The shaded area defines the process window. Oven efficiency, board size/mass, component type and density all influence the final profile for a given assembly. These profiles are starting points, and processing boards with thermal-couples attached is recommended to optimize the process. For other assemblies requiring this high melting point alloy, best results are achieved using a linear ramp rate profile that reaches a peak temperature of 325°C ± 5°C as fast as possible. Please contact Technical Services for any additional questions or concerns.



<i>RATE OF RISE 1.5-2°C / SEC MAX</i>	<i>RAMP TO 170°C (338°F)</i>	<i>PROGRESS THROUGH 170°C-230°C (302°F-446°F)</i>	<i>TO PEAK TEMP 320°C-330°C (608°F-626°F)</i>	<i>TIME ABOVE 301°C (574°F)</i>	<i>COOLDOWN ≤ 4 °C / SEC</i>	<i>PROFILE LENGTH AMBIENT TO PEAK</i>
Initial Profile	≤ 75 Sec	45-100 Sec	45-75 Sec	30-60 Sec	45 ± 15 Sec	3.5-4.0 Min

❖ THE RECOMMENDED REFLOW PROFILE IS PROVIDED AS A GUIDELINE. OPTIMAL PROFILE MAY DIFFER DUE TO OVEN TYPE, ASSEMBLY LAYOUT, OR OTHER PROCESS VARIABLES. CONTACT AIM TECHNICAL SUPPORT IF YOU REQUIRE ADDITIONAL PROFILING ASSISTANCE.

Compatible Products:

- AIM Lead-Free Electropure Solder Bar
- NC Paste Flux, No-Clean Tacky Flux
- NC270WR VOC-Free No-Clean Spray Flux
- NC264-5 No-Clean Flux Spray/Foam
- Glowcore No-Clean Cored Wire
- One-Step Underfill FF35
- Epoxy 4044 Chip Bonding Epoxy

Cleaning:

- RMA258-15R is a rosin based formula that may be cleaned if necessary with saponified water or an appropriate solvent cleaner.
- Please refer to the AIM cleaner matrix for a list of compatible cleaning materials.

Handling and Storage:

- RMA258-15R is best used within 9 months at 4° C-12° C (40° F-55° F) or 4 months at room temperature.
- Allow the solder paste to warm up completely and naturally to ambient temperature (8 hrs.) prior to breaking the seal for use.
- Mix the product lightly and thoroughly (1-2 mins. max) to ensure even distribution of any separated material.
- Do not store new and used paste in the same container, and reseal any opened containers while not in use.
- Replace the internal plug and cap of the 500 gram jars to ensure the best possible seal.

Physical Properties:

<i>ITEM</i>	<i>SPECIFICATION</i>
Appearance	Gray, Smooth, Creamy
Alloy	Sn10/Pb88/Ag2
Melting Point	268° - 290° C
Particle Size	T3, T4, T5
Viscosity	Print/dispense versions available.
Packaging	Available in all industry standard packaging.

Test Data Summary:

CLASSIFICATION			
Product Name	IPC Classification to J-STD-004	Copper Mirror to J-STD-004	Silver Chromate to J-STD-004
RMA258-15R	ROL0	LOW	PASS
POWDER TESTING			
No.	Item	Results	Test Method
1	Powder Size	Type 3 – 45-25 micron Type 4 – 38-20 micron	IPC TM 650 2.2.14
2	Powder Shape	Spherical	Microscope
FLUX MEDIUM TESTING			
No.	Item	Results	Test Method
1	Acid Value	133.08 mg KOH/ g flux	J-STD-004 IPC TM 650 2.3.13
2	Halide Content	Silver Chromate Paper - Pass	J-STD-004 IPC TM 650 2.3.35
3	Fluorides Spot Test	No fluoride	J-STD-004 IPC TM 650 2.3.35.1 J-STD-004 IPC TM 650 2.3.35.2
4	Corrosion Flux	Pass	J-STD-004 IPC TM 650 2.6.15
5	Halide-Free/Silver Chromate Paper Test	Pass	J-STD-004 IPC TM 650 2.3.33
6	Surface Insulation Resistance	Pass – See AIM Qualification Test Report	J-STD-004 IPC TM 650 2.6.3.7
7	Oxygen Bomb	Bromine 269 mg/Kg Chlorine <99.9 mg/Kg	EN 14582:2007 SW 9056 SW 5050
VISCOSITY TESTING			
No.	Item	Results	Test Method
1	T-Bar Spindle Test Method	900 ± 10% kcps	J-STD-005 IPC TM 650 2.4.34
SOLDER PASTE TESTING			
No.	Item	Results	Test Method
1	Tack Test	48.8 g	J-STD-005 IPC TM 650 2.4.44
2	Tack Test	94.8 g	JIS Z 3284 Annex 9
3	Solder Ball Test	Pass	J-STD-005 IPC TM 650 2.4.43
4	Wetting Test	Pass	J-STD-005 IPC TM 650 2.4.45
5	Paste Shelf Life	4°C (39°F) = 9 months	AIM TM 125-11
6	Solder Paste Slump Test	Pass	J-STD-005 IPC TM 650 2.4.35

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 AIM IS ISO9001:2008 & ISO14001:2004 CERTIFIED

The information contained herein is based on data considered accurate and is offered at no charge. Product information is based upon the assumption of proper handling and operating conditions. All information pertaining to solder paste is produced with 45-micron powder. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated. Please refer to <http://www.aimsolder.com/Home/TermsConditions.aspx> to review AIM's terms and conditions.